

MA3X158 (MA158)

Silicon epitaxial planar type

For small power rectification and surge absorption

■ Features

- High reverse voltage V_R
- Large forward current (Average) $I_{F(AV)}$
- Automatic mounting is possible

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Repetitive peak reverse voltage	V_{RRM}	250	V
Non-repetitive peak reverse surge voltage	V_{RSM}	300	V
Output current	I_O	100	mA
Repetitive peak forward current	I_{FRM}	225	mA
Non-repetitive peak forward surge current*	I_{FSM}	500	mA
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

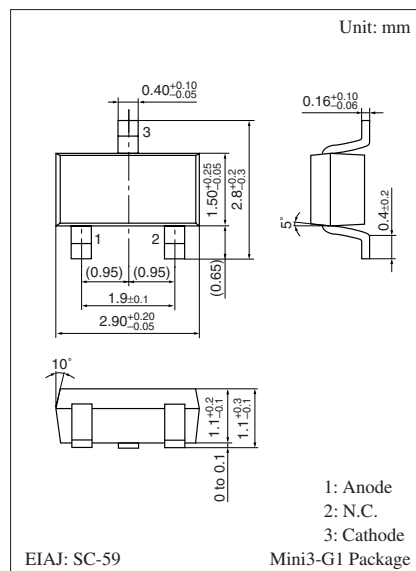
Note) *: $t = 1\text{ s}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100\text{ mA}$			1.3	V
Reverse current	I_R	$V_R = 200\text{ V}$			1.0	μA

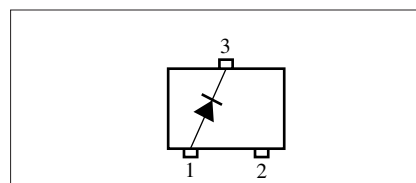
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 3 MHz.

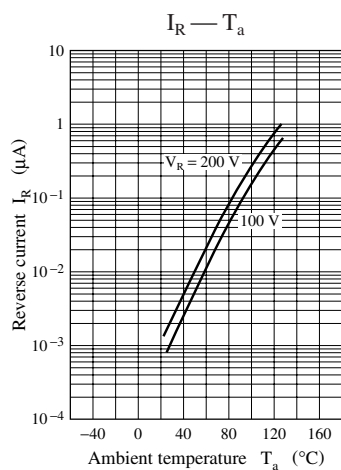
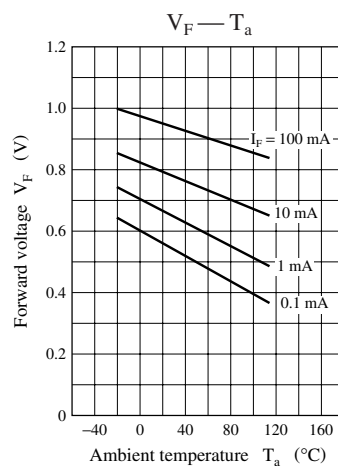
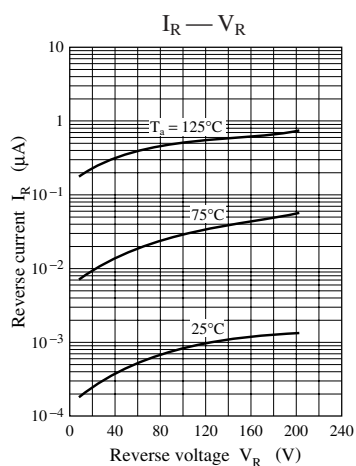
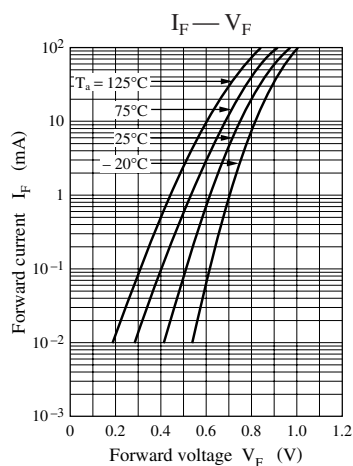


Marking Symbol: M1C

Internal Connection



Note) The part number in the parenthesis shows conventional part number.



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